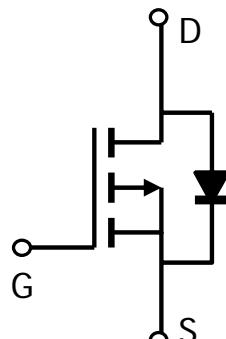


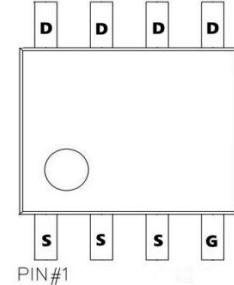
General Description

The AO4485 uses advanced trench technology to provide excellent $R_{DS(ON)}$ with low gate charge. This device is suitable for use as a DC-DC converter application.



Features

V_{DS} (V) = -40V
 I_D = -10A
 $R_{DS(ON)} < 15m\Omega$ ($V_{GS} = -10V$)
 $R_{DS(ON)} < 20m\Omega$ ($V_{GS} = -4.5V$)



Absolute Maximum Ratings $T_J=25^\circ C$ unless otherwise noted

Parameter		Symbol	10 Sec	Steady State	Units
Drain-Source Voltage		V_{DS}		-40	V
Gate-Source Voltage		V_{GS}		± 20	V
Continuous Drain Current ^A	$T_A=25^\circ C$	I_D	-12	-10	A
	$T_A=70^\circ C$		-9	-8	
Pulsed Drain Current ^B		I_{DM}		-120	
Avalanche Current ^G		I_{AR}		-28	
Repetitive avalanche energy $L=0.3mH$ ^G		E_{AR}		118	mJ
Power Dissipation ^A	$T_A=25^\circ C$	P_D	3.1	1.7	W
	$T_A=70^\circ C$		2.0	1.1	
Junction and Storage Temperature Range		T_J, T_{STG}		-55 to 150	°C

Thermal Characteristics

Parameter		Symbol	Typ	Max	Units
Maximum Junction-to-Ambient ^A	$t \leq 10s$	$R_{\theta JA}$	31	40	°C/W
Maximum Junction-to-Ambient ^A	Steady State		59	75	°C/W
Maximum Junction-to-Lead ^C	Steady State	$R_{\theta JL}$	16	24	°C/W

Electrical Characteristics ($T_J=25^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Conditions	Min	Typ	Max	Units
STATIC PARAMETERS						
BV_{DSS}	Drain-Source Breakdown Voltage	$I_D = -250\mu\text{A}, V_{GS} = 0\text{V}$	-40			V
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = -40\text{V}, V_{GS} = 0\text{V}$ $T_J = 55^\circ\text{C}$		-1		μA
				-5		
I_{GSS}	Gate-Body leakage current	$V_{DS} = 0\text{V}, V_{GS} = \pm 20\text{V}$			± 100	nA
$V_{GS(\text{th})}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = -250\mu\text{A}$	-1	-1.5	-2.5	V
$I_{D(\text{ON})}$	On state drain current	$V_{GS} = -10\text{V}, V_{DS} = -5\text{V}$	-120			A
$R_{DS(\text{ON})}$	Static Drain-Source On-Resistance	$V_{GS} = -10\text{V}, I_D = -10\text{A}$		12.5	15	$\text{m}\Omega$
		$V_{GS} = -4.5\text{V}, I_D = -8\text{A}$		16	20	
g_{FS}	Forward Transconductance	$V_{DS} = -5\text{V}, I_D = -10\text{A}$		25		S
V_{SD}	Diode Forward Voltage	$I_S = -1\text{A}, V_{GS} = 0\text{V}$		-0.7	-1	V
I_S	Maximum Body-Diode Continuous Current				-3	A
DYNAMIC PARAMETERS						
C_{iss}	Input Capacitance	$V_{GS}=0\text{V}, V_{DS}=-20\text{V}, f=1\text{MHz}$		2500	3000	pF
C_{oss}	Output Capacitance			260		pF
C_{rss}	Reverse Transfer Capacitance			180		pF
R_g	Gate resistance	$V_{GS}=0\text{V}, V_{DS}=0\text{V}, f=1\text{MHz}$	2.5	4	6	Ω
SWITCHING PARAMETERS						
$Q_g(10\text{V})$	Total Gate Charge	$V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, I_D=-10\text{A}$		42	55	nC
$Q_g(4.5\text{V})$	Total Gate Charge			18.6		nC
Q_{gs}	Gate Source Charge			7		nC
Q_{gd}	Gate Drain Charge			8.6		nC
$t_{D(\text{on})}$	Turn-On DelayTime	$V_{GS}=-10\text{V}, V_{DS}=-20\text{V}, R_L=2\Omega, R_{\text{GEN}}=3\Omega$		9.4		ns
t_r	Turn-On Rise Time			20		ns
$t_{D(\text{off})}$	Turn-Off DelayTime			55		ns
t_f	Turn-Off Fall Time			30		ns
t_{rr}	Body Diode Reverse Recovery Time	$I_F=-10\text{A}, dI/dt=100\text{A}/\mu\text{s}$		38	49	ns
Q_{rr}	Body Diode Reverse Recovery Charge	$I_F=-10\text{A}, dI/dt=100\text{A}/\mu\text{s}$		47		nC

A: The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A = 25^\circ\text{C}$. The value in any given application depends on the user's specific board design.

B: Repetitive rating, pulse width limited by junction temperature.

C. The $R_{\theta JA}$ is the sum of the thermal impedance from junction to lead $R_{\theta JL}$ and lead to ambient.

D. The static characteristics in Figures 1 to 6 are obtained using $t \leq 300\mu\text{s}$ pulses, duty cycle 0.5% max.

E. These tests are performed with the device mounted on 1 in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The SOA curve provides a single pulse rating.

F. The current rating is based on the $t \leq 10\text{s}$ thermal resistance rating.

G. E_{AR} and I_{AR} ratings are based on low frequency and duty cycles to keep $T_J=25\text{C}$.

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

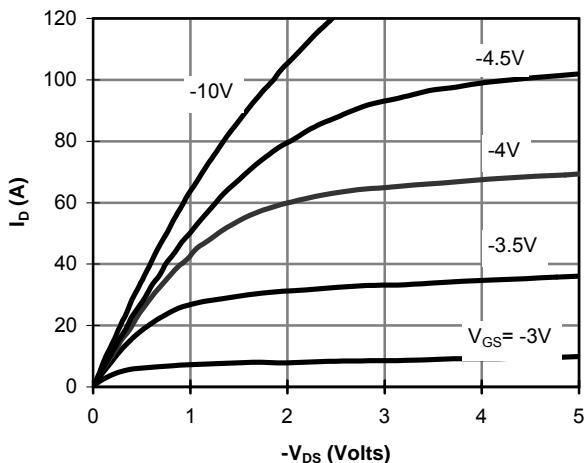


Figure 1: On-Region Characteristics

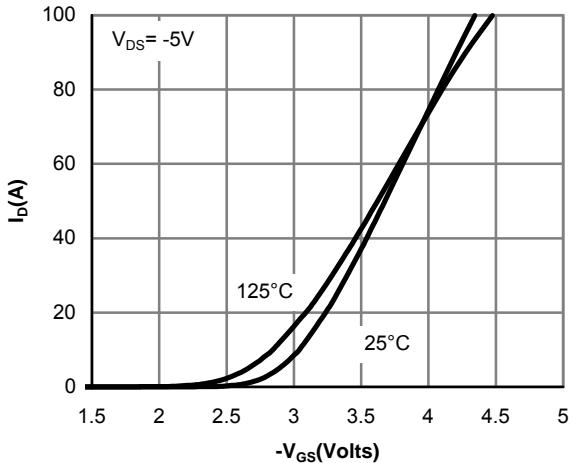


Figure 2: Transfer Characteristics

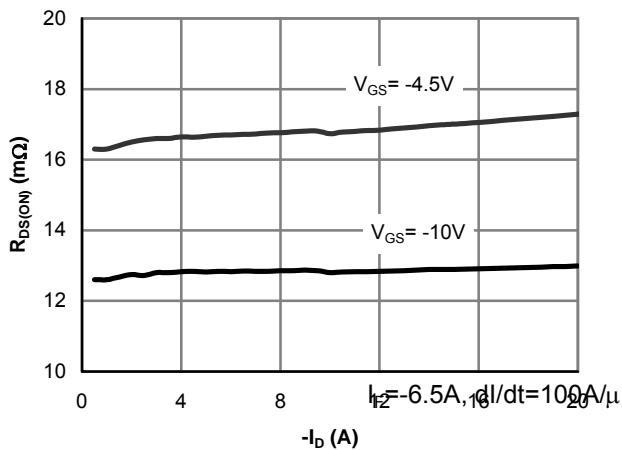


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

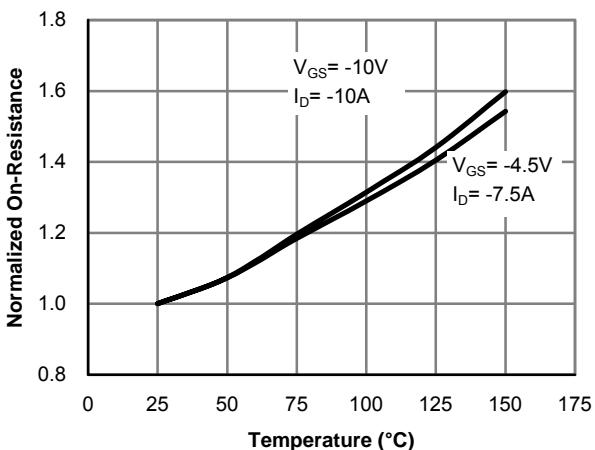


Figure 4: On-Resistance vs. Junction Temperature

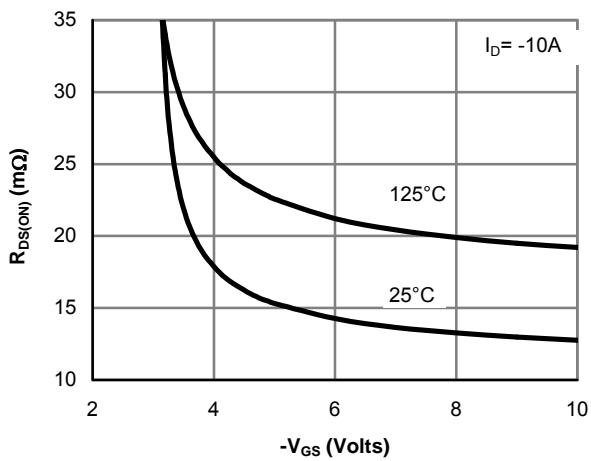


Figure 5: On-Resistance vs. Gate-Source Voltage

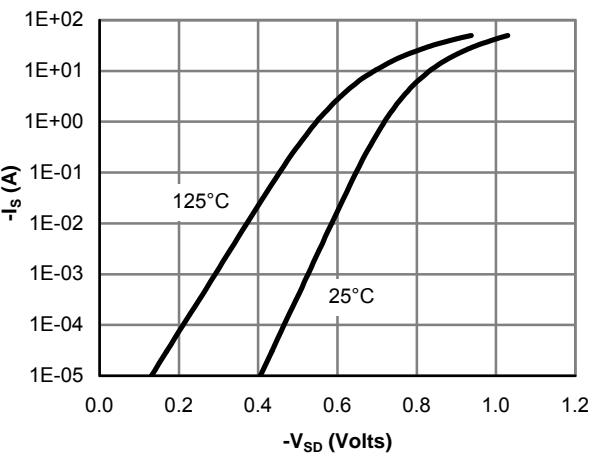


Figure 6: Body-Diode Characteristics

TYPICAL ELECTRICAL AND THERMAL CHARACTERISTICS

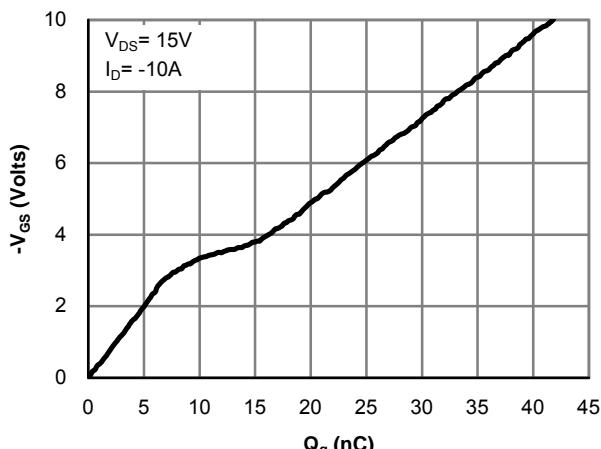


Figure 7: Gate-Charge Characteristics

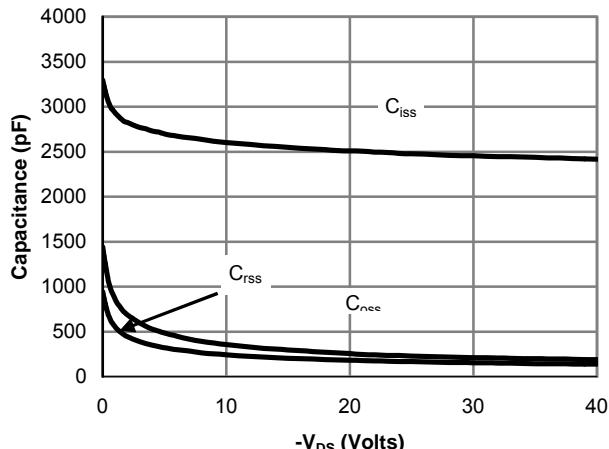


Figure 8: Capacitance Characteristics

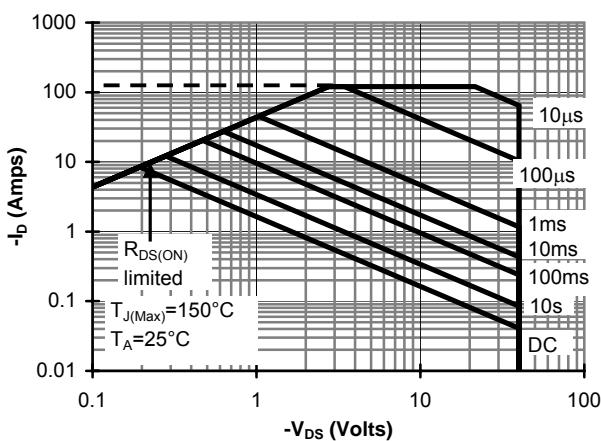


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

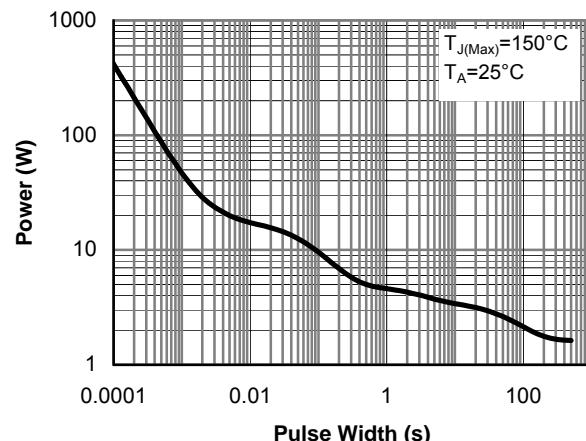


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

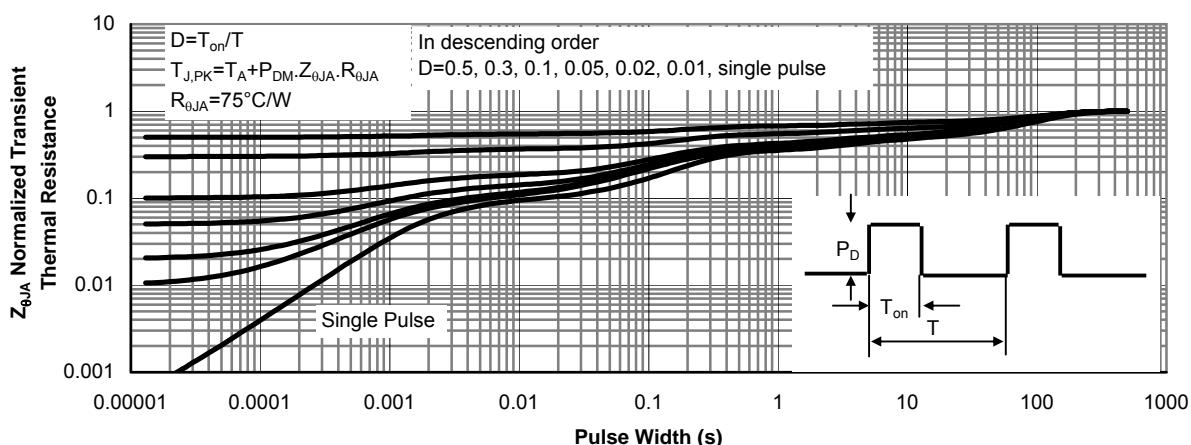
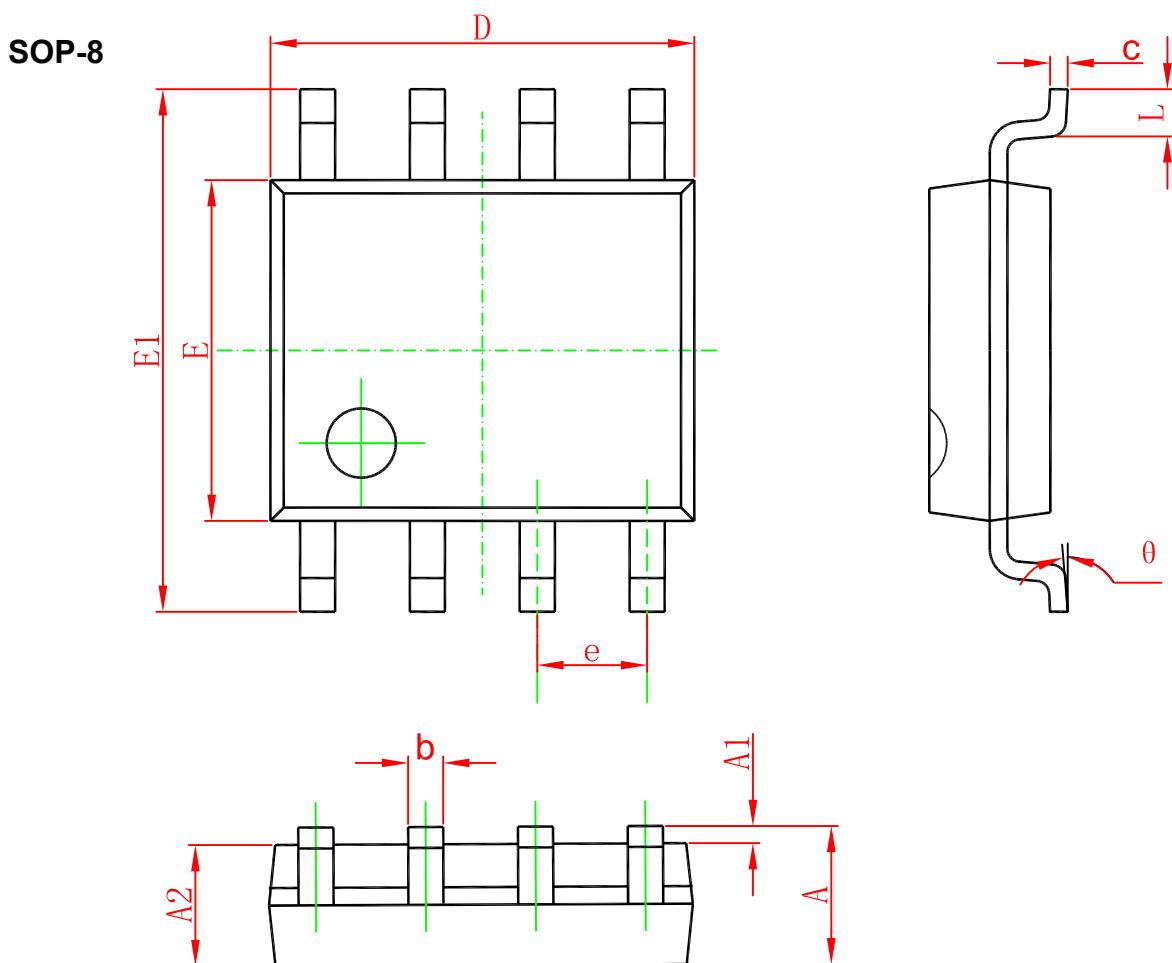


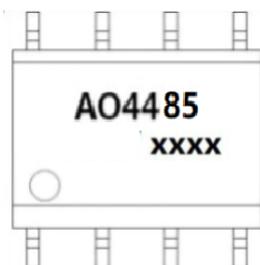
Figure 11: Normalized Maximum Transient Thermal Impedance (Note E)

PACKAGE OUTLINE DIMENSIONS



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

Marking



("xxxx"代表年份周期)

Ordering information

Order code	Package	Baseqty	Deliverymode
AO4485	SOP-8	3000	Tape and reel